

Temperature Sensor ICs

Low current Thermostat Output

BDJxxx1HFV Series

General Description

BDJxxx1HFV series is a thermostat output temperature sensor IC with built-in temperature detection element, constant current circuit, and a high-accuracy reference voltage source in one chip. Temperature detection can be realized at $\pm 2.5^{\circ}\text{C}$ accuracy without the need for a complicated design. It is the best suited for portable equipment of micro- and low-current, power down function, and battery drive. It is possible to use it for a wide range of applications such as heat detection and temperature monitors because it provides an analog output in addition to the thermostat power output. BDJxxx1HFV series has 6 products at 60°C , 70°C , 75°C , 80°C , 85°C and 90°C detection temperature.

Features

- Detection Temperature lineup at 60°C , 70°C , 75°C , 80°C , 85°C , 90°C (6 products)
- Built-in power down control function. (Min PD interface Voltage is 1.5V)
- Low thermal resistance package (Typ $187^{\circ}\text{C}/\text{W}$)
- ESD Rating of 8kV (HBM)
- OS Output Active H

Applications

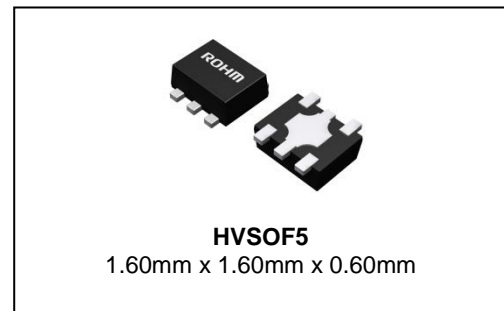
Cellular Phone, Digital Camera, Thermal Protection for Electrical Equipment (Notebook PC, FPD-TV, etc.)

Key Specifications

- Power Supply Voltage Range: 2.4V to 5.5V
- Supply Current:
 - Normal Function mode 7.5 μA (Typ)
 - Power Down mode 0.3 μA (Typ)
- High Accuracy Thermostat:
 - $\pm 2.5^{\circ}\text{C}$ (Max) @ $T_a=60^{\circ}\text{C}$ to $+90^{\circ}\text{C}$
- Sensing Temperature Hysteresis: 10.0°C (Typ)
- High Accuracy Analog Output:
 - $\pm 2.5^{\circ}\text{C}$ (Max) @ $T_a=-30^{\circ}\text{C}$ to $+100^{\circ}\text{C}$
- Analog Output Temperature Sensitivity:
 - 8.2 mV/ $^{\circ}\text{C}$ (Typ)
- Operating Temperature Range: -30°C to $+100^{\circ}\text{C}$

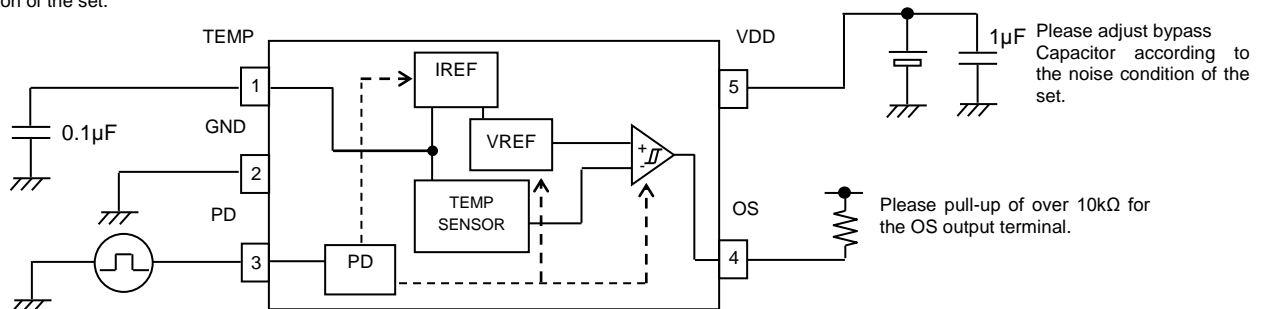
Package

W(Typ) x D(Typ) x H(Max)

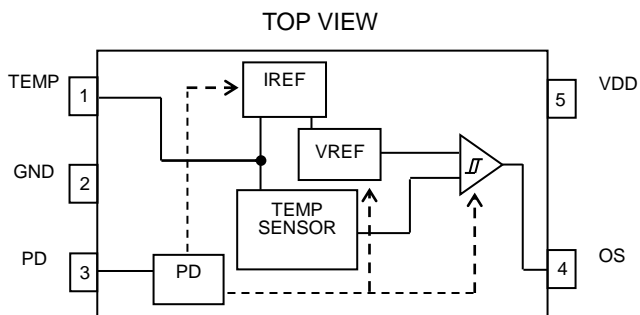


Typical Application Circuit

Please adjust capacitor according to the noise condition of the set.



Block Diagram and Pin Configuration



Pin Descriptions

Pin No.	Pin Name	Function	Comment
1	TEMP	Output voltage in inverse proportion to the Temperature	Set to Open state or connect to a high input impedance node (over 10M Ω).
2	GND	Ground	
3	PD	Power Down Control H: Normal Function mode L: Power Down mode	H: Thermostat and Analog Output operation. L: Power Down state.
4	OS	Digital Thermostat Output	Open-Drain Active-High. Use pull-up resistor of more than 10k Ω .
5	VDD	Power Supply Voltage	

Absolute Maximum Ratings (Ta = 25°C)

Parameter	Symbol	Rating	Unit
Power Supply Voltage	V _{DD}	-0.3 to +7.0 (Note 1)	V
Input Voltage (Pd)	V _{IN}	-0.3 to +V _{DD} +0.3	V
OS Terminal Voltage	V _{OS}	-0.3 to +7.0 (Note 1)	V
OS Terminal Current	I _{OS}	5.0	mA
Power Dissipation	P _d	0.53 (Note 2)	W
Storage Temperature Range	T _{stg}	-55 to +150	°C

(Note 1) However, not exceeding Pd.

(Note 2) When mounted on ROHM standard board, derate by 5.36mW/°C for Ta higher than 25 °C.

Caution: Operating the IC over the absolute maximum ratings may damage the IC. The damage can either be a short circuit between pins or an open circuit between pins and the internal circuitry. Therefore, it is important to consider circuit protection measures, such as adding a fuse, in case the IC is operated over the absolute maximum ratings.

Recommended Operating Conditions

Parameter	Symbol	Rating			Unit
		Min	Typ	Max	
Power Supply Voltage	V _{DD}	2.4	2.8	5.5	V
Operating Temperature Range	T _{opr}	-30	-	+100	°C

Electrical Characteristics (Unless otherwise specified, V_{DD} = 2.8V, Ta = 25°C)

Parameter	Symbol	Limit			Unit	Conditions
		Min	Typ	Max		
Supply Current						
Normal Function Mode	I _{DD}	-	7.5	12.0	μA	PD="H"
Power Down Mode	I _{DDPD}	-	0.3	1.0	μA	PD="L"
PD						
Input L Voltage	V _{IL}	GND	-	0.2	V	
Input H Voltage	V _{IH}	1.5	-	V _{DD}	V	
PD Leakage Current	I _{LPD}	-	-	1.0	μA	PD=2.8V
Analog Output						
TEMP Output Voltage	V _{TEMP}	1.279	1.300	1.321	V	Ta = 30°C
TEMP Temperature Sensitivity	V _{SE}	-8.00	-8.20	-8.40	mV/°C	Ta = -30°C to +100°C
TEMP Load Regulation	ΔV _{TEMPRL}	-	-	1.0	mV	difference of I _{OUT} : 0μA / 2μA
TEMP VDD Regulation	ΔV _{TEMPVDD}	-	-	4.0	mV	V _{DD} =2.4V to 5.5V
OS Output Open Drain						
OS Leakage Current	I _L	-	-	1.0	μA	V _{OS} = 5.0V
OS Output Voltage	V _{OL}	-	-	0.4	V	I _{OS} = 1.0mA

Radiation hardness is not designed.

Temperature Accuracy (Unless otherwise specified, V_{DD} = 2.8V)

Parameter	Symbol	Limit			Unit	Conditions
		Min	Typ	Max		
Thermostat						
Sensing Temperature Accuracy	T _{acc}	-	-	±2.5	°C	
Sensing Temperature Hysteresis	Thys	7.5	10.0	12.5	°C	
Analog Output						
TEMP Temperature Accuracy	T _{TEMP}	-	-	±2.5	°C	V _{DD} = 2.8V Ta = -30°C to +100°C

Typical Performance Curves

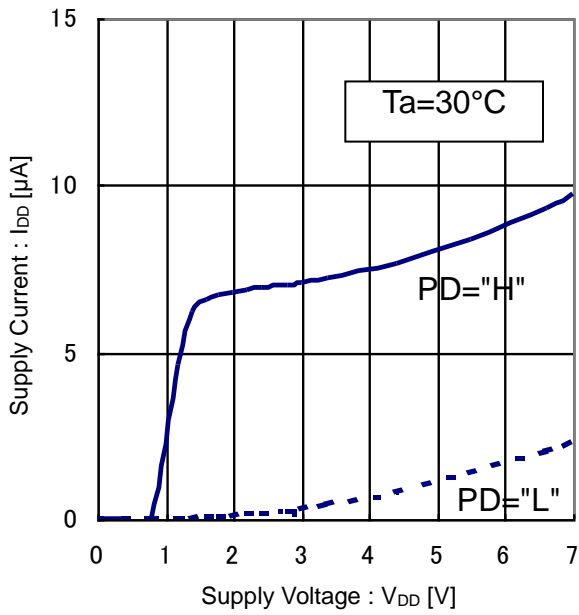


Figure 1. Supply Current vs Supply Voltage

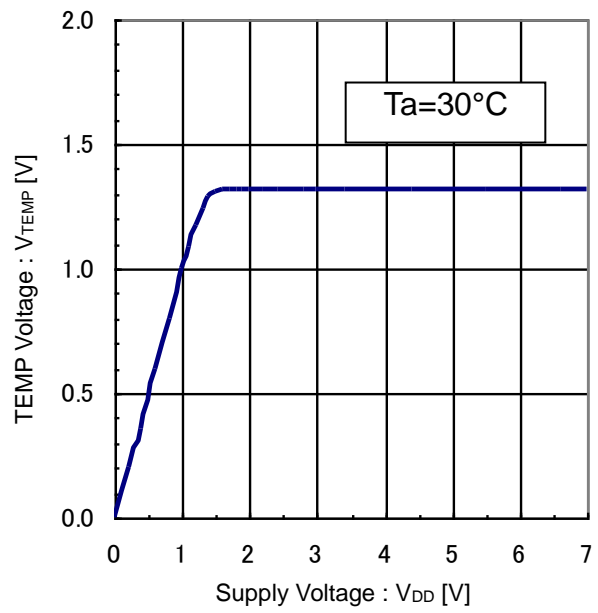


Figure 2. TEMP Voltage vs Supply Voltage

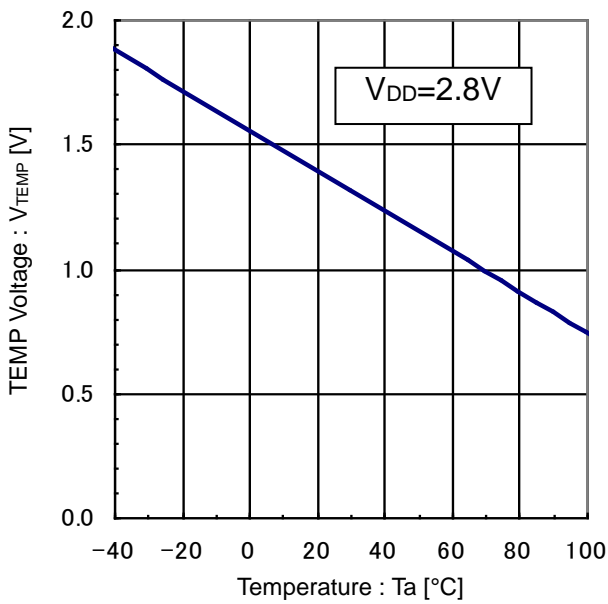


Figure 3. TEMP Voltage vs Temperature

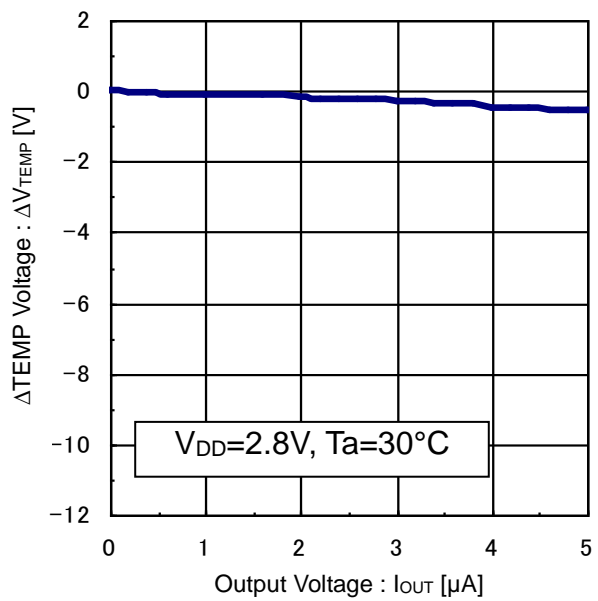


Figure 4. TEMP Voltage vs Output Current

Typical Performance Curves – continued

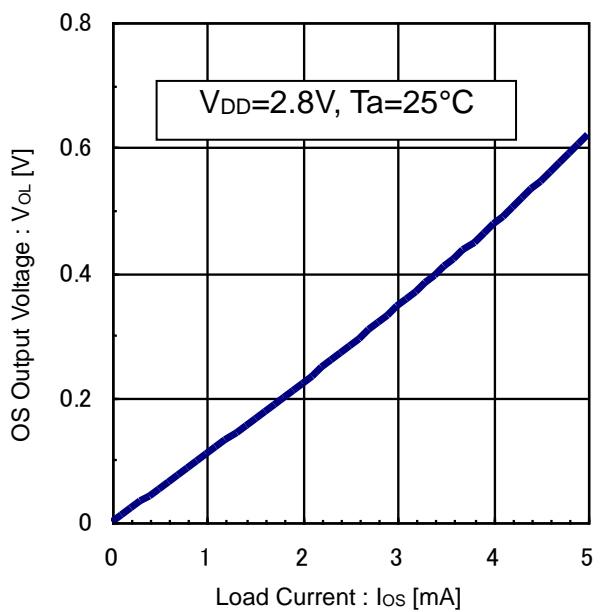
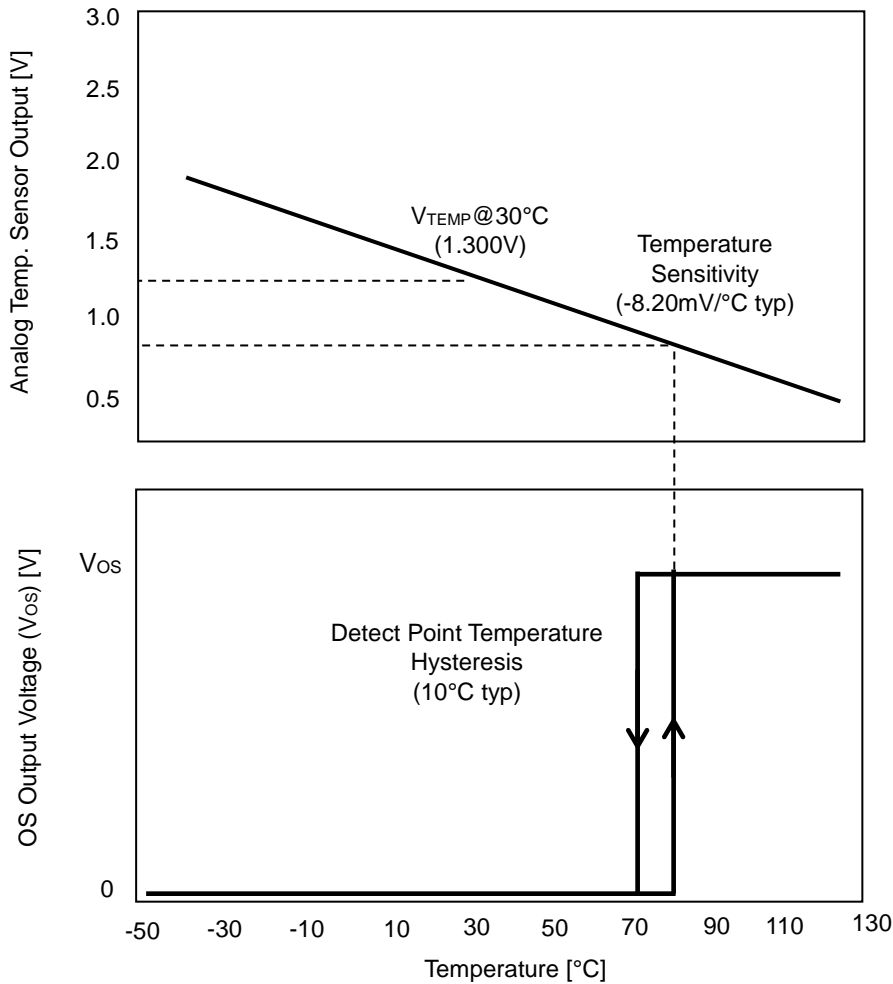


Figure 5. OS Output Voltage vs Load Current

Application Information

1. Function Diagram (ex. 80°C detect Active-H type BDJ0801HFV)

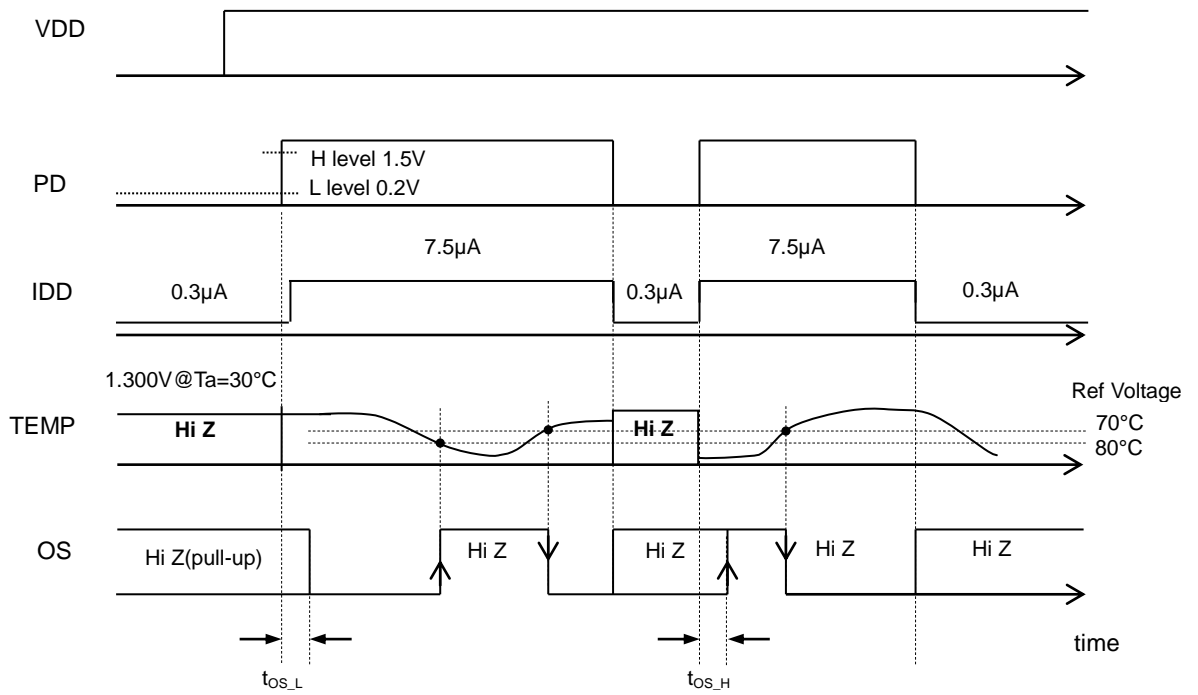
The internal IC temperature sensor senses temperature. TEMP terminal output voltage is converted to temperature. V_{TEMP} value is 1.300[V] at $T_a = 30[^\circ\text{C}]$. The value of V_{TEMP} voltage reduction is inversely proportional to the temperature at a rate of $-8.2\text{mV}/^\circ\text{C}$.



If the temperature exceeds the detect point temperature, the internal comparator forces the OS output to change from “L” to “H”. (ex. Active-H Type)
 OS returns to “L” when the temperature becomes 10°C lower than the detect point temperature.

2. Operation Sequence

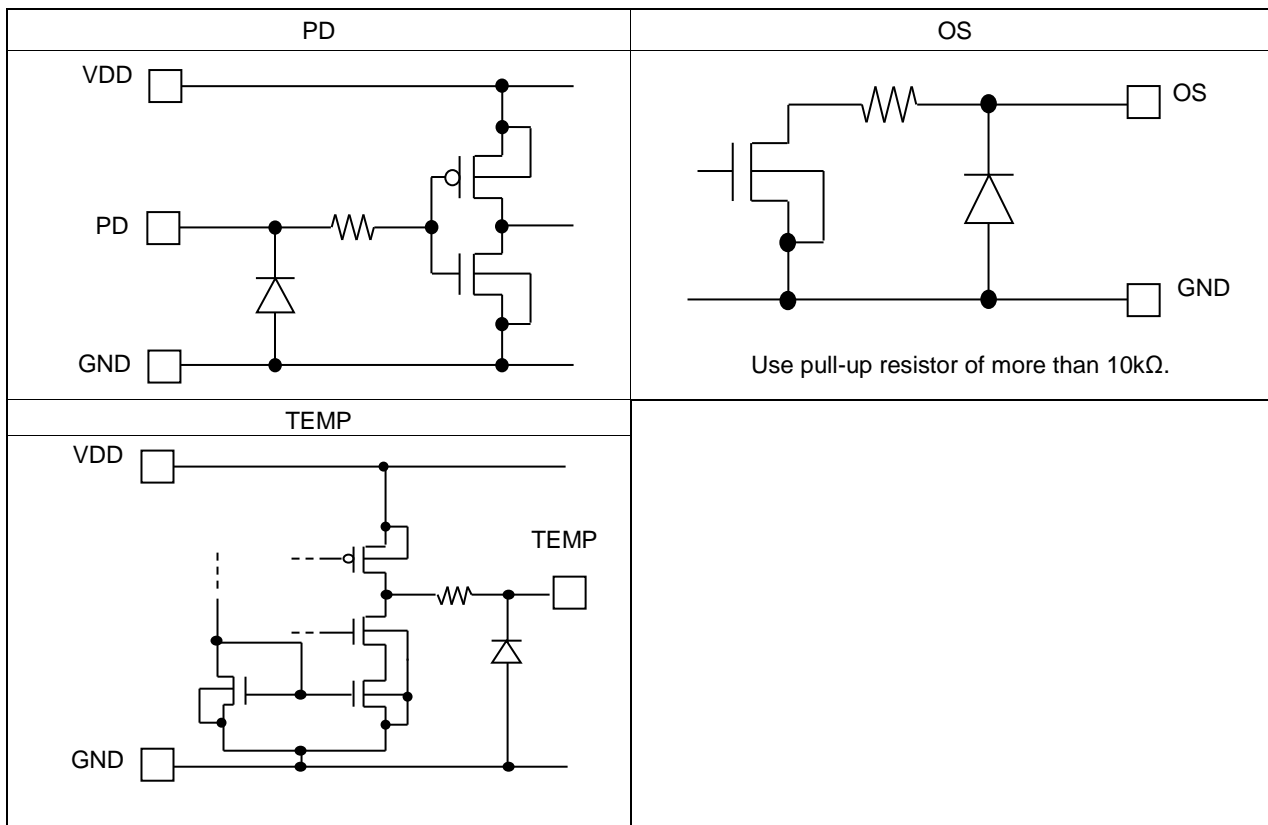
(ex. 80°C detect Active-H type BDJ0801HFV)



BDJ0801HFV operation starts after PD “H” Input.
Please refer to the OS terminal signal table below for the wait time after PD “H” Input.

Ta	Symbol	Wait time
Under detect Temp.	t_{os_L}	200µs
Over detect Temp.	t_{os_H}	1000µs

I/O Equivalent Circuits



Operational Notes**1. Reverse Connection of Power Supply**

Connecting the power supply in reverse polarity can damage the IC. Take precautions against reverse polarity when connecting the power supply, such as mounting an external diode between the power supply and the IC's power supply pins.

2. Power Supply Lines

Design the PCB layout pattern to provide low impedance supply lines. Separate the ground and supply lines of the digital and analog blocks to prevent noise in the ground and supply lines of the digital block from affecting the analog block. Furthermore, connect a capacitor to ground at all power supply pins. Consider the effect of temperature and aging on the capacitance value when using electrolytic capacitors.

3. Ground Voltage

Ensure that no pins are at a voltage below that of the ground pin at any time, even during transient condition.

4. Ground Wiring Pattern

When using both small-signal and large-current ground traces, the two ground traces should be routed separately but connected to a single ground at the reference point of the application board to avoid fluctuations in the small-signal ground caused by large currents. Also ensure that the ground traces of external components do not cause variations on the ground voltage. The ground lines must be as short and thick as possible to reduce line impedance.

5. Thermal Consideration

Should by any chance the power dissipation rating be exceeded the rise in temperature of the chip may result in deterioration of the properties of the chip. In case of exceeding this absolute maximum rating, increase the board size and copper area to prevent exceeding the Pd rating.

6. Recommended Operating Conditions

These conditions represent a range within which the expected characteristics of the IC can be approximately obtained. The electrical characteristics are guaranteed under the conditions of each parameter.

7. Inrush Current

When power is first supplied to the IC, it is possible that the internal logic may be unstable and inrush current may flow instantaneously due to the internal powering sequence and delays, especially if the IC has more than one power supply. Therefore, give special consideration to power coupling capacitance, power wiring, width of ground wiring, and routing of connections.

8. Operation Under Strong Electromagnetic Field

Operating the IC in the presence of a strong electromagnetic field may cause the IC to malfunction.

9. Testing on Application Boards

When testing the IC on an application board, connecting a capacitor directly to a low-impedance output pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from the test setup during the inspection process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.

10. Inter-pin Short and Mounting Errors

Ensure that the direction and position are correct when mounting the IC on the PCB. Incorrect mounting may result in damaging the IC. Avoid nearby pins being shorted to each other especially to ground, power supply and output pin. Inter-pin shorts could be due to many reasons such as metal particles, water droplets (in very humid environment) and unintentional solder bridge deposited in between pins during assembly to name a few.

Operational Notes – continued

11. Unused Input Pins

Input pins of an IC are often connected to the gate of a MOS transistor. The gate has extremely high impedance and extremely low capacitance. If left unconnected, the electric field from the outside can easily charge it. The small charge acquired in this way is enough to produce a significant effect on the conduction through the transistor and cause unexpected operation of the IC. So unless otherwise specified, unused input pins should be connected to the power supply or ground line.

12. Regarding the Input Pin of the IC

This monolithic IC contains P+ isolation and P substrate layers between adjacent elements in order to keep them isolated. P-N junctions are formed at the intersection of the P layers with the N layers of other elements, creating a parasitic diode or transistor. For example (refer to figure below):

When GND > Pin A and GND > Pin B, the P-N junction operates as a parasitic diode.
 When GND > Pin B, the P-N junction operates as a parasitic transistor.

Parasitic diodes inevitably occur in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Therefore, conditions that cause these diodes to operate, such as applying a voltage lower than the GND voltage to an input pin (and thus to the P substrate) should be avoided.

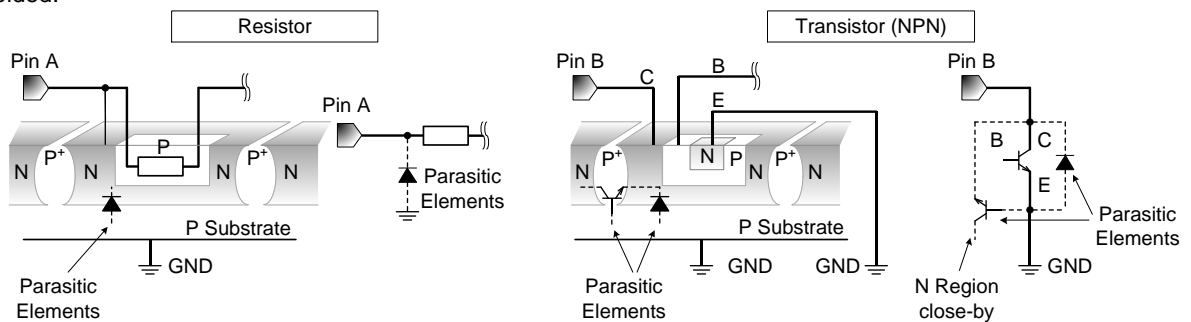
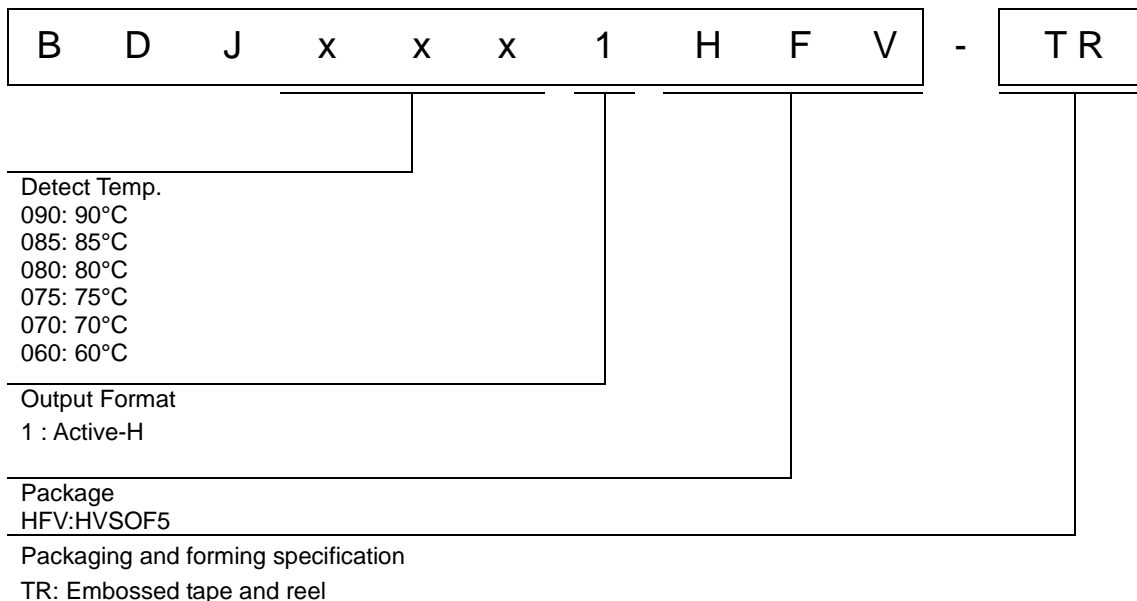


Figure 6. Example of monolithic IC structure

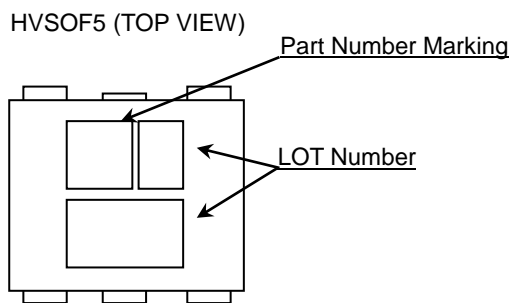
Ordering Information



Lineup

Product Name	Detect Temp. (°C)	OS Output Format		Product Name	Detect Temp. (°C)	OS Output Format	
BDJ0901HFV	90	Open Drain	Active H	BDJ0751HFV	75	Open Drain	Active H
BDJ0851HFV	85	Open Drain	Active H	BDJ0701HFV	70	Open Drain	Active H
BDJ0801HFV	80	Open Drain	Active H	BDJ0601HFV	60	Open Drain	Active H

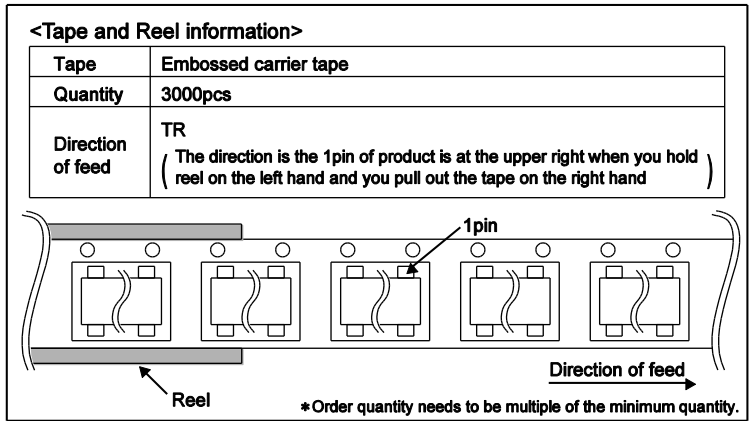
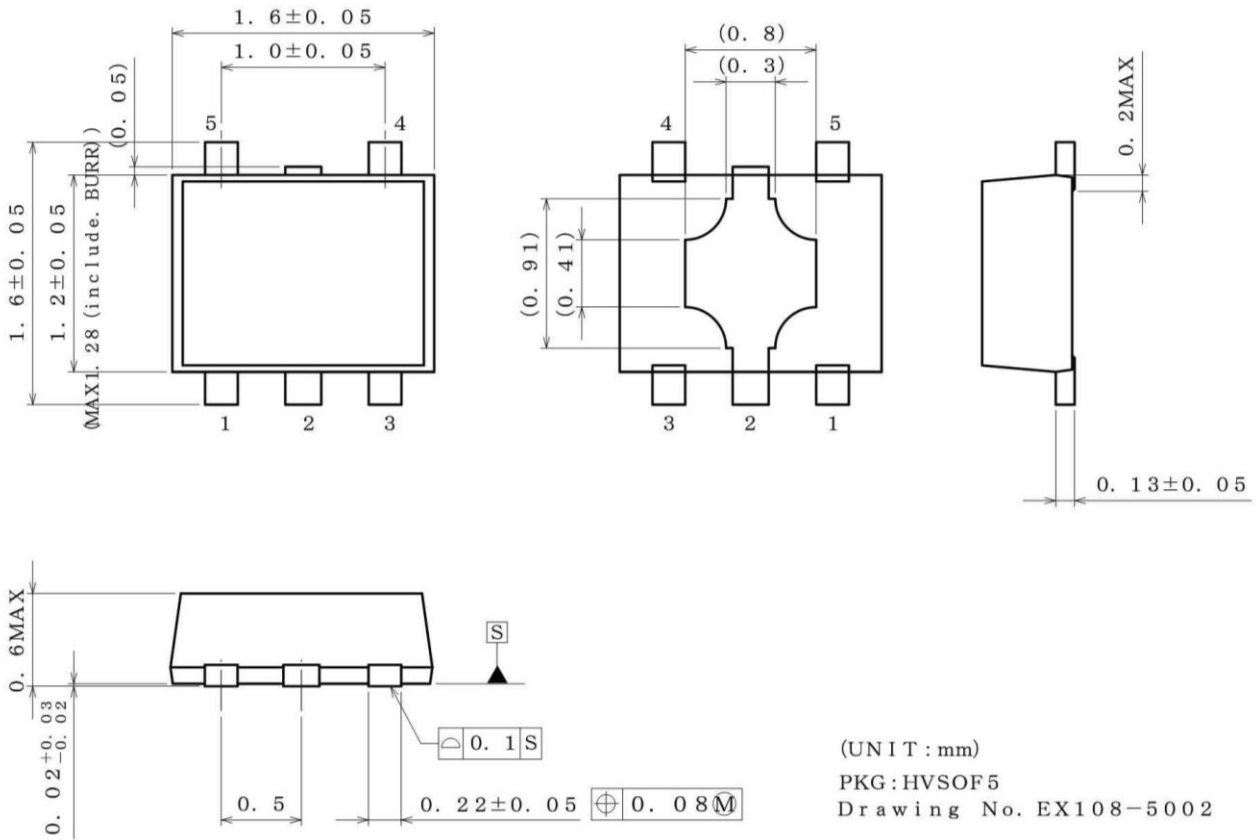
Marking Diagram



Orderable Part Number	Part Number Marking
BDJ0901HFV-TR	gd
BDJ0851HFV-TR	ge
BDJ0801HFV-TR	gf
BDJ0751HFV-TR	gg
BDJ0701HFV-TR	gh
BDJ0601HFV-TR	gm

Physical Dimension, Tape and Reel Information

Package Name	HVSOF5
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Revision History

Date	Revision	Changes
06.Nov.2015	001	New Release

Notice

Precaution on using ROHM Products

- Our Products are designed and manufactured for application in ordinary electronic equipments (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment ^(Note 1), transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASS III	CLASS III	CLASS II b	CLASS III
CLASS IV		CLASS III	

- ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
 - Installation of protection circuits or other protective devices to improve system safety
 - Installation of redundant circuits to reduce the impact of single or multiple circuit failure
- Our Products are designed and manufactured for use under standard conditions and not under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc. prior to use, must be necessary:
 - Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
 - Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - Sealing or coating our Products with resin or other coating materials
 - Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - Use of the Products in places subject to dew condensation
- The Products are not subject to radiation-proof design.
- Please verify and confirm characteristics of the final or mounted products in using the Products.
- In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

Precautions Regarding Application Examples and External Circuits

1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of Ionizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

Precaution for Product Label

QR code printed on ROHM Products label is for ROHM's internal use only.

Precaution for Disposition

When disposing Products please dispose them properly using an authorized industry waste company.

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Since concerned goods might be fallen under listed items of export control prescribed by Foreign exchange and Foreign trade act, please consult with ROHM in case of export.

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